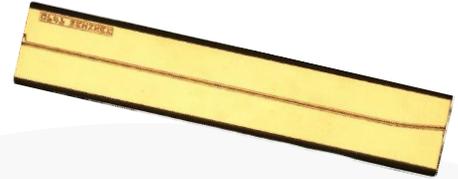


# High Power RSOA Chip



## Part Number: CHP-289

High Power RSOA Chip  
Single-Mode RSOA Fabry-Perot  
Wavelength at 1310nm



## Features

- High Output Power
- High Dynamic Range
- High Efficiency
- Standard ROSA Bare Die
- Cost Effective

## Application

- OTDR
- LiDAR
- Free Space Communications
- Network Test Equipment



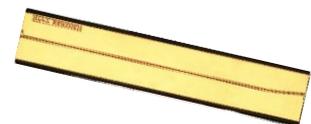
SemiNex delivers the highest available power at infrared wavelengths between 12xx and 19xx nm. When necessary, we will further optimize the design of our InP & GaSb laser chips to meet our customers' specific optical and electrical performance needs. Diodes, bars, and packages are tested to meet customer and market performance demands. Typical results and packaging options are shown. Contact SemiNex for additional details or to discuss your specific requirements.

# High Power RSOA Chip



## Specification

CHP-289



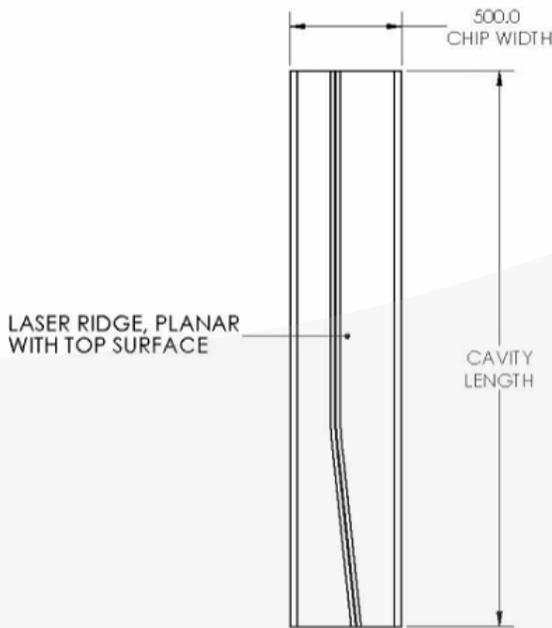
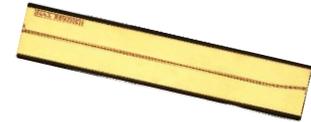
Optical	Symbol	Typ.	Units
Center Wavelength	$\lambda_c$	1310	nm
Aperture Width	AW	4	$\mu\text{m}$
Aperture Height	AH	1	$\mu\text{m}$
Beam Exit Angle	$\theta_{EXT}$	19.5	Degree
Noise Figure	NF	6	dB
Polarization Extinction Ratio	PER	18	dB
Fast Axis Div.	$\theta_{\perp}$	28	Deg FWHM
Slow Axis Div.	$\theta_{\parallel}$	16	Deg FWHM
Front Facet Reflectivity		<0.1%	
Rear Face Reflectivity		98%	
Waveguide		Curved	
Electrical	Symbol		Units
Operating Current	$I_{op}$	1	A
Operating Voltage	$V_{op}$	2	V
Mechanical		Range	Units
Chip Length		2500	$\mu\text{m}$
Chip Width		500	$\mu\text{m}$
Operating Temp.**		-20 to 75	$^{\circ}\text{C}$
Storage Temp.		-40 to 85	$^{\circ}\text{C}$

Specified values are rated at a constant heat sink temperature of 20°C.  
 \*\*High temperature operation will reduce performance and MTF.  
 Unless otherwise indicated all values are nominal.

# High Power RSOA Chip



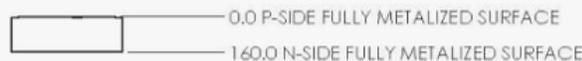
## Mechanical Drawing



CHIP ATTRIBUTES	
WAVELENGTH	1550nm ±20nm
APERTURE WIDTH	4µm ±1µm
CHIP WIDTH	0.500mm ±10µm
THICKNESS	160µm ±10µm
CAVITY LENGTH	2.5mm ±10µm

P-METAL		
MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	50	±10
Pt	125	±25
Au	250	±50

N-METAL		
MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	30	±10
Pt	125	±25
Au	400	±40



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